

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
SHUNICHI IWATA	04/20/2009
YOICHI TAKAHATA	04/21/2009
TOSHIHIKO SUGAHARA	04/20/2009
YUTAKA TAKIKAWA	04/21/2009
YOSHIHIRO SHIMIZU	04/21/2009
HIROKI ISHIKURO	03/25/2009
TADAHIRO KURODA	03/24/2009

**RECEIVING PARTY DATA**

Name:	Renesas Technology Corp.
Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

Name:	Keio University
Street Address:	15-45, Mita 2-chome
City:	Minato-ku, Tokyo
State/Country:	JAPAN
Postal Code:	108-8345

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12514023

**CORRESPONDENCE DATA**

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*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
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CH \$40.00 12514023

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ATTORNEY DOCKET NUMBER:

XA-11365/T3662-17220US01

NAME OF SUBMITTER:

Mitchell W. Shapiro

Total Attachments: 2  
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# ASSIGNMENT

( 讓 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS TECHNOLOGY CORP., a corporation organized under the laws of Japan, located at 6-2 ,Otemachi 2-chome ,Chiyoda-ku, Tokyo, Japan, and KEIO UNIVERSITY a university organized under the laws of Japan, located at 15-45, Mita 2-chome, Minato-ku, Tokyo 108-8345, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS TECHNOLOGY CORP., and KEIO UNIVERSITY its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## SYSTEM DEBUGGING METHOD, SYSTEM DEBUGGING EQUIPMENT, PROCESSOR, WIRELESS-COMMUNICATIONS INTERFACE IC AND INTERFACE METHOD THEREOF

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., and KEIO UNIVERSITY their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP., and KEIO UNIVERSITY

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) ( 発 明 者 フ ル ネ ー ム サ イ ン )	Date Signed ( 署 名 日 )
1)	<u>Shunichi Iwata</u> (Shunichi IWATA)	<u>April 20, 2009</u>
2)	<u>Yoichi Takahata</u> (Yoichi TAKAHATA)	<u>April, 21, 2009</u>
3)	<u>Toshihiko Sugahara</u> (Toshihiko SUGAHARA)	<u>April, 20, 2009</u>
4)	<u>Yutaka Takikawa</u> (Yutaka TAKIKAWA)	<u>April, 21, 2009</u>
5)	<u>Yoshihiro Shimizu</u> (Yoshihiro SHIMIZU)	<u>April, 21, 2009</u>
6)	_____ (Hiroki ISHIKURO)	_____
7)	_____ (Tadahiro KURODA)	_____

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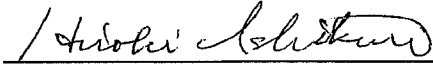
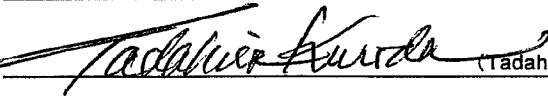
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WIRELESS-COMMUNICATIONS INTERFACE IC AND INTERFACE METHOD THEREOF

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., and KEIO UNIVERSITY their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP., and KEIO UNIVERSITY

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ (Shunichi IWATA)	_____
2) _____ (Yoichi TAKAHATA)	_____
3) _____ (Toshihiko SUGAHARA)	_____
4) _____ (Yutaka TAKIKAWA)	_____
5) _____ (Yoshihiro SHIMIZU)	_____
6) <u></u> (Hiroki ISHIKURO)	<u>March 25, 2009</u>
7) <u></u> (Tadahiro KURODA)	<u>March 24, 2009</u>
8) _____	_____